

## GENERAL DESCRIPTION

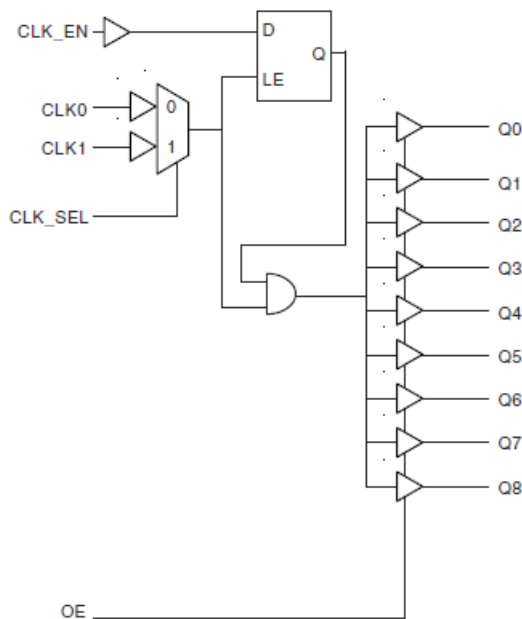
The 83947I is a low skew, 1-to-9 LVCMOS Fanout Buffer. The low impedance LVCMOS/LVTTL outputs are designed to drive 50Ω series or parallel terminated transmission lines. The effective fanout can be increased from 9 to 18 by utilizing the ability of the outputs to drive two series terminated lines.

Guaranteed output and part-to-part skew characteristics make the 83947I ideal for high performance, single ended applications that also require a limited output voltage.

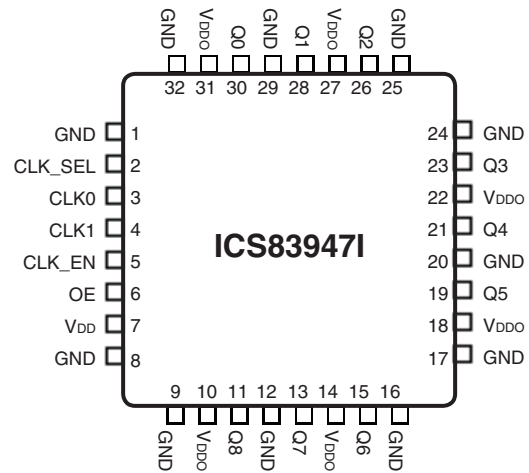
## FEATURES

- 9 LVCMOS/LVTTL outputs
- Selectable CLK0 and CLK1 can accept the following input levels: LVCMOS and LVTTL
- Maximum output frequency: 110MHz
- Output skew: 500ps (maximum)
- Part-to-part skew: 2ns (maximum)
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- Lead-Free package available

## BLOCK DIAGRAM



## PIN ASSIGNMENT



**32-Lead LQFP**  
7mm x 7mm x 1.4mm package body  
**Y Package**  
Top View

**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1, 8, 9, 12, 16, 17, 20, 24, 25, 29, 32	GND	Power		Power supply ground.
2	CLK_SEL	Input	Pullup	Clock select input. When HIGH, selects CLK1. When LOW, selects CLK0. LVCMOS / LVTTTL interface levels.
3, 4	CLK0, CLK1	Input	Pullup	Reference clock inputs. LVCMOS / LVTTTL interface levels.
5	CLK_EN	Input	Pullup	Clock enable. LVCMOS / LVTTTL interface levels.
6	OE	Input	Pullup	Output enable. LVCMOS / LVTTTL interface levels.
7	V <sub>DD</sub>	Power		Core supply pin.
10, 14, 18, 22, 27, 31	V <sub>DDO</sub>	Power		Output supply pins.
11, 13, 15, 19, 21, 23, 26, 28, 30	Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Q0 thru Q8 clock outputs. LVCMOS / LVTTTL interface levels.

NOTE: *Pullup* refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)			25		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		KΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		KΩ
R <sub>OUT</sub>	Output Impedance		5	7	12	Ω

**TABLE 3. OUTPUT ENABLE AND CLOCK ENABLE FUNCTION TABLE**

Control Inputs		Output
OE	CLK_EN	Q0:Q8
0	X	Hi-Z
1	0	LOW
1	1	Follows CLK input

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $V_O$	-0.5V to $V_{DDO} + 0.5V$
Package Thermal Impedance, $\theta_{JA}$	47.9°C/W (0 lpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 3.3V \pm 0.3V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Coret Supply Voltage		3.0	3.3	3.6	V
$V_{DDO}$	Output Supply Voltage		3.0	3.3	3.6	V
$I_{DD}$	Input Supply Current			33	50	mA

**TABLE 4B. LVCMOS/LVTTL DC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 3.3V \pm 0.3V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage		2		3.6	V
$V_{IL}$	Input Low Voltage				0.8	V
$I_{IN}$	Input Current	CLK0, CLK1, CLK_SEL, OE, CLK_EN	-100			$\mu\text{A}$
$V_{OH}$	Output High Voltage	$I_{OH} = -20\text{mA}$	2.5			V
$V_{OL}$	Output Low Voltage	$I_{OL} = 20\text{mA}$			0.4	V

**TABLE 5. AC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 3.3V \pm 0.3V$ ,  $T_A = -40^{\circ}C$  TO  $85^{\circ}C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency		110			MHz
$t_{PD}$	Propagation Delay, NOTE 1	CLK to Q	1.8		4.5	ns
tsk(o)	Output Skew; NOTE 2, 5	Measured on rising edge @ $V_{DDO}/2$			500	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 5	Measured on rising edge @ $V_{DDO}/2$			2	ns
$t_{PW}$	Output Pulse Width		tPeriod/2 - 800		tPeriod/2 + 800	ps
$t_S$	Clock Enable Setup Time; NOTE 6	CLK_EN to CLK	0			ns
$t_H$	Clock Enable Hold Time; NOTE 6	CLK_EN to CLK	1			ns
$t_{ZL}, t_{ZH}$	Output Enable Time; NOTE 4				11	ns
$t_{LZ}, t_{HZ}$	Output Disable Time; NOTE 4				11	ns
$t_R$	Output Rise Time	0.8V to 2.0V	0.2		1	ns
$t_F$	Output Fall Time	0.8V to 2.0V	0.2		1	ns

All parameters measured at  $f_{MAX}$  unless noted otherwise.

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at  $V_{DDO}/2$ .

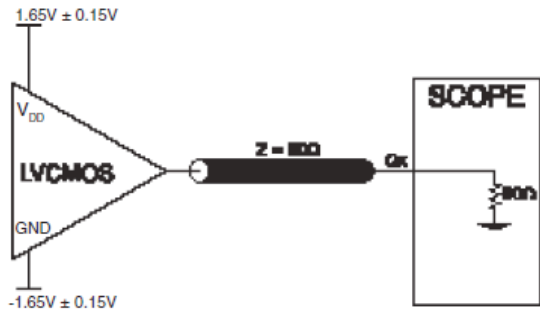
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 4: These parameters are guaranteed by characterization. Not tested in production.

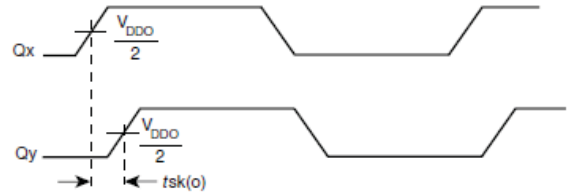
NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Setup and Hold times are relative to the rising edge of the input clock.

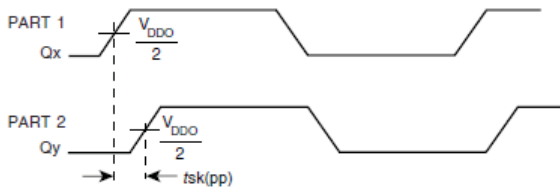
## PARAMETER MEASUREMENT INFORMATION



3.3V OUTPUT LOAD AC TEST CIRCUIT



OUTPUT SKEW



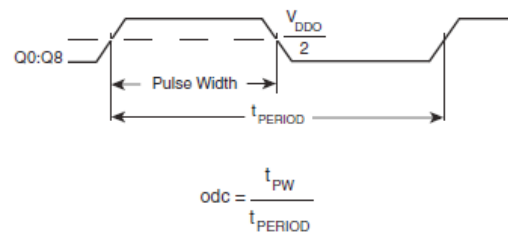
PART-TO-PART SKEW



PROPAGATION DELAY



OUTPUT RISE/FALL TIME



OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

## RELIABILITY INFORMATION

TABLE 6.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 32 LEAD LQFP

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for 839471 is: 1040

PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

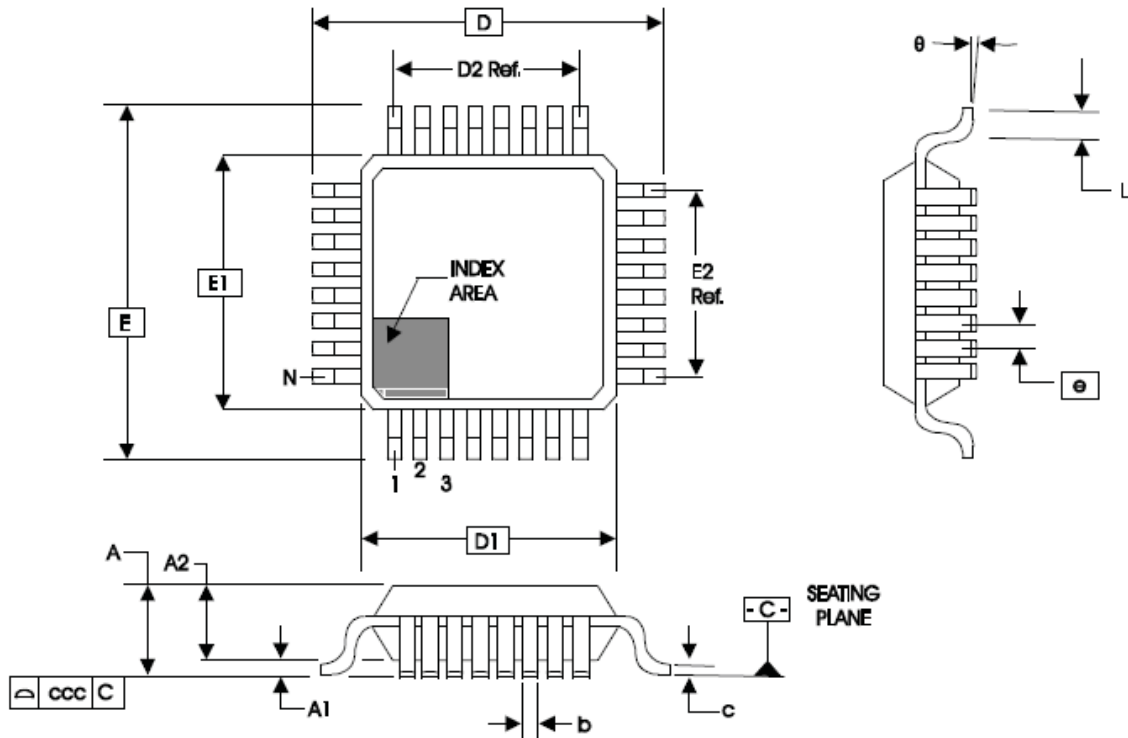


TABLE 7. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS			
SYMBOL	BBA		
	MINIMUM	NOMINAL	MAXIMUM
N	32		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.30	0.37	0.45
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.60 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.60 Ref.		
e	0.80 BASIC		
L	0.45	0.60	0.75
θ	0°	--	7°
ccc	--	--	0.10

Reference Document: JEDEC Publication 95, MS-026

**TABLE 8. ORDERING INFORMATION**

<b>Part/Order Number</b>	<b>Marking</b>	<b>Package</b>	<b>Shipping Packaging</b>	<b>Temperature</b>
83947AYILN	ICS3947AYIN	32 Lead "Lead-Free/Annealed" LQFP	tray	-40°C to 85°C
83947AYILNT	ICS3947AYIN	32 Lead "Lead-Free/Annealed" LQFP	Tape & Reel	-40°C to 85°C



REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
A	T5	4	AC Characteristics Table, $t_s$ and $t_H$ rows- revised Test Conditions to read CLK_EN to CLK.	6/21/02
B	T2	1	Added Lead Free bullet in Features section.	10/11/04
	T8	2	Pin Characteristics Table - changed $C_{IN}$ from 4pF max. to 4pF min. $R_{OUT}$ added 5 $\Omega$ min and 12 $\Omega$ max.	
B	T8	8	Ordering Information Table - add Lead-Free part.	8/9/10
		10	Updated format throughout data sheet.	
B	T8	8	Updated datasheet's header/footer with IDT from ICS.	11/10/14
		10	Removed ICS prefix from Part/Order Number column. Added Contact Page.	
B	T8	8	Updated datasheet format Ordering information - removed leaded part numbers - PDN CQ-13-02 expired	3/17/16
B			Removed ICS from part number where needed. Updated header and footer.	



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